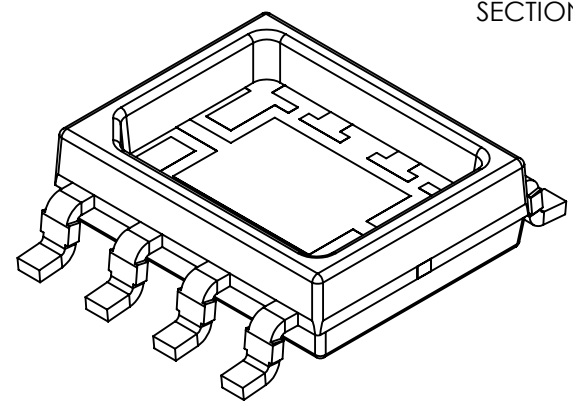
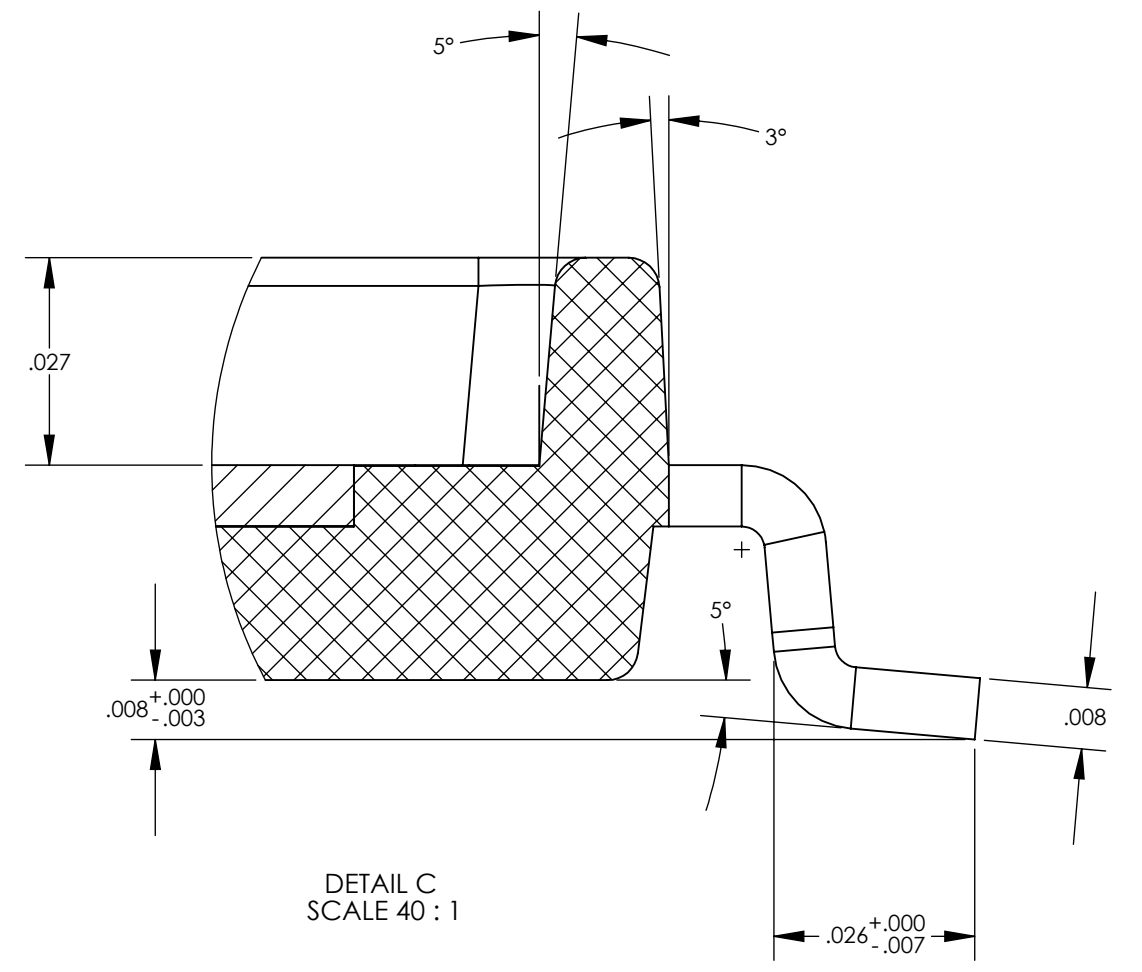
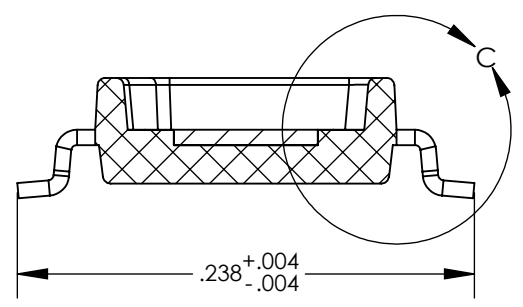
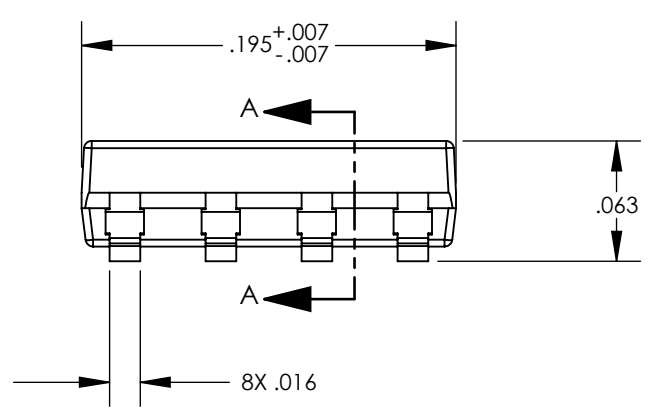
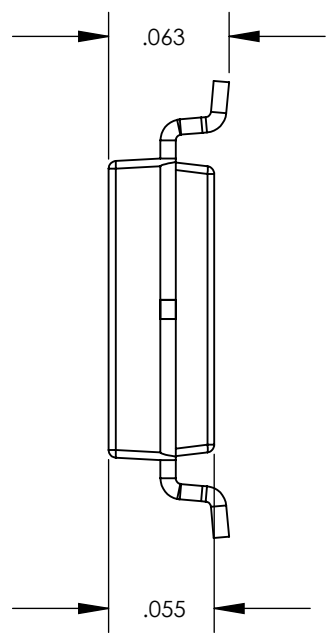
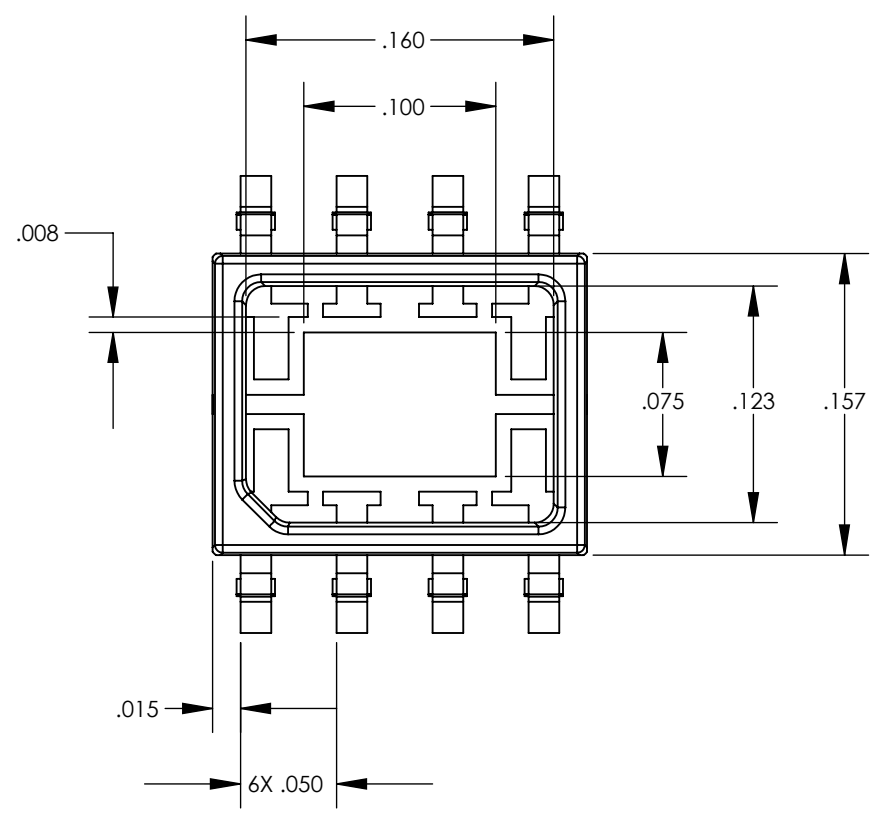


8 7 6 5 4 3 2 1

REVISIONS				
ZONE	REV.	DESCRIPTION	DATE	APPROVED
	A	ORIGINAL RELEASE	7/16/12	SS

D
C
B
A



SECTION A-A

DETAIL C
SCALE 40 : 1

3. PACKAGE CONFORMS TO JEDEC MS-012.
2. FINISH: LEAD FRAME ELECTROLESS NICKEL PER MIL-C-26075, CLASS 1, 100 TO 300 MICROINCHES (2.5um - 7.6um) THICK. GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1.
1. MATERIALS: LEAD FRAME, COPPER ALLOY 194 FULL HARD. BODY: SEMICONDUCTOR GRADE MOLDING EPOXY.

PROPRIETARY AND CONFIDENTIAL
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		UNLESS OTHERWISE SPECIFIED:				NAME		DATE	
		DIMENSIONS ARE IN INCHES TOLERANCES ARE:		DRAWN		S. Swen		7/5/12	
		FRACTIONAL: ± 1/16"		CHECKED		S. Swen		7/6/12	
		ANGULAR: ±0.5 degree		ENG APPR.		S. Swen		7/12/12	
		.X = ±.030 .XX: ±.010							
		.XXX = ±.005 .XXXX = ±.0005							
		MATERIAL		COMMENTS:					
		SEE NOTE 1.							
NEXT ASSY		USED ON		FINISH					
				SEE NOTE 2.					
APPLICATION				DO NOT SCALE DRAWING					
				TITLE:		SIZE		DWG. NO.	
				SOIC, 8 LD, .150 WIDE PACKAGE OUTLINE DRAWING		B		500520	
				SCALE: 10:1		WEIGHT:		REV	
								A	
				SHEET 1 OF 1					

QUIK-PAK 10987 VIA FRONTERA
SAN DIEGO, CA 92127
858-674-4676

SCALE: 10:1 WEIGHT: SHEET 1 OF 1

8 7 6 5 4 3 2 1